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Intel - EPM7128EQC160-20 Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	100
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	160-BQFP
Supplier Device Package	160-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128eqc160-20

Email: info@E-XFL.COM

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Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-tooutput performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

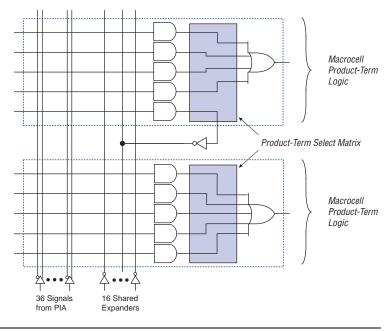
Expander Product Terms

Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. Figure 5 shows how shareable expanders can feed multiple macrocells.

Figure 5. Shareable Expanders



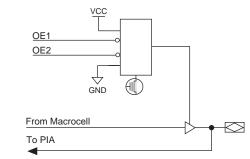
Shareable expanders can be shared by any or all macrocells in an LAB.

Parallel Expanders

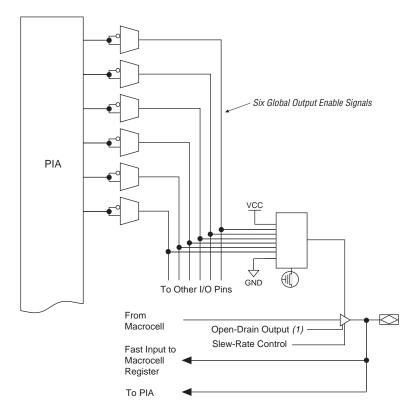
Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices







Note:

(1) The open-drain output option is available only in MAX 7000S devices.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$
where: t_{PROG} = Programming time
 t_{PPULSE} = Sum of the fixed times to erase, program, and
verify the EEPROM cells
 $Cycle_{PTCK}$ = Number of TCK cycles to program a device
 f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$
where: t_{VER} = Verify time
 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When V_{CCIO} is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When V_{CCIO} is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the Programming Hardware Manufacturers.

Programming with External Hardware

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-S	Table 10. MAX 7000S Boundary-Scan Register Length									
Device	Boundary-Scan Register Length									
EPM7032S	1 (1)									
EPM7064S	1 (1)									
EPM7128S	288									
EPM7160S	312									
EPM7192S	360									
EPM7256S	480									

Note:

 This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32-Bit MAX 7000 Device IDCODE Note (1)												
Device		IDCODE (32 B	lits)									
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)								
EPM7032S	0000	0111 0000 0011 0010	00001101110	1								
EPM7064S	0000	0111 0000 0110 0100	00001101110	1								
EPM7128S	0000	0111 0001 0010 1000	00001101110	1								
EPM7160S	0000	0111 0001 0110 0000	00001101110	1								
EPM7192S	0000	0111 0001 1001 0010	00001101110	1								
EPM7256S	0000	0111 0010 0101 0110	00001101110	1								

Notes:

(1) The most significant bit (MSB) is on the left.

(2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

devices.

Figure 9 shows the timing requirements for the JTAG signals.

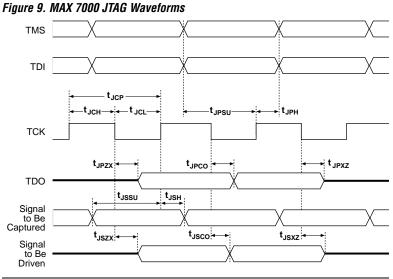


Table 12 shows the JTAG timing parameters and values for MAX 7000S

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Мах	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*).

Operating Conditions

Tables 13 through 18 provide information about absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for 5.0-V MAX 7000 devices.

Table 13. MAX 7000 5.0-V Device Absolute Maximum Ratings Note (1)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply voltage	With respect to ground (2)	-2.0	7.0	V
VI	DC input voltage		-2.0	7.0	V
I _{OUT}	DC output current, per pin		-25	25	mA
T _{STG}	Storage temperature	No bias	-65	150	°C
T _{AMB}	Ambient temperature	Under bias	-65	135	°C
TJ	Junction temperature	Ceramic packages, under bias		150	°C
		PQFP and RQFP packages, under bias		135	°C

Table 1	4. MAX 7000 5.0-V Device Reco	ommended Operating Conditions			
Symbol	Parameter	Conditions	Min	Мах	Unit
V _{CCINT}	Supply voltage for internal logic and input buffers	(3), (4), (5)	4.75 (4.50)	5.25 (5.50)	V
V _{CCIO}	Supply voltage for output drivers, 5.0-V operation	(3), (4)	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	(3), (4), (6)	3.00 (3.00)	3.60 (3.60)	V
V _{CCISP}	Supply voltage during ISP	(7)	4.75	5.25	V
VI	Input voltage		-0.5 (8)	V _{CCINT} + 0.5	V
Vo	Output voltage		0	V _{CCIO}	V
T _A	Ambient temperature	For commercial use	0	70	°C
		For industrial use	-40	85	°C
TJ	Junction temperature	For commercial use	0	90	°C
		For industrial use	-40	105	°C
t _R	Input rise time			40	ns
t _F	Input fall time			40	ns

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	0E (-10P)		00 (-10) Doe (-10)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t _{SU}	Register setup time		2.0		3.0		ns
t _H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	OE (-12P)		00 (-12) DOE (-12)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			1.0		2.0	ns
t _{IO}	I/O input pad and buffer delay			1.0		2.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			7.0		7.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0	ns
t _{LAD}	Logic array delay			7.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		1.0		3.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		6.0		6.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		7.0		7.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		10.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t _{SU}	Register setup time		1.0		4.0		ns
t _H	Register hold time		6.0		4.0		ns
t _{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns
t _{FH}	Register hold time of fast input	(2)	0.0		2.0		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			7.0		5.0	ns
t _{GLOB}	Global control delay			2.0		0.0	ns
t _{PRE}	Register preset time			4.0		3.0	ns
t _{CLR}	Register clear time			4.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		12.0	ns

	5. MAX 7000 & MAX 7000E	-	aramete		lote (1)				
Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-15T		-20		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{SU}	Global clock setup time		11.0		11.0		12.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	3.0		-		5.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.0		-		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t _{CH}	Global clock high time		5.0		6.0		6.0		ns
t _{CL}	Global clock low time		5.0		6.0		6.0		ns
t _{ASU}	Array clock setup time		4.0		4.0		5.0		ns
t _{AH}	Array clock hold time		4.0		4.0		5.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t _{ACH}	Array clock high time		6.0		6.5		8.0		ns
t _{ACL}	Array clock low time		6.0		6.5		8.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			13.0		13.0		16.0	ns
fcnt	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t _{ACNT}	Minimum array clock period			13.0		13.0		16.0	ns
f _{acnt}	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f _{MAX}	Maximum clock frequency	(6)	100		83.3		83.3		MHz

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-5		-6		-7		-10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{odh}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 3	0. EPM7064S Internal Tir	ning Parameters	s (Part à	2 of 2)	No	te (1)						
Symbol	Parameter	Conditions	Speed Grade									
			-	-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns	
t _{RD}	Register delay			1.2		1.6		1.0		2.0	ns	
t _{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns	
t _{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns	
t _{EN}	Register enable time			2.6		3.2		3.0		5.0	ns	
t _{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns	
t _{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns	
t _{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns	
t _{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns	
t _{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns	

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter (2) must be added to this minimum width if the clear or reset signal incorporates the t_{IAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- The f_{MAX} values represent the highest frequency for pipelined data. (5)
- Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use. (6)
- For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, (7) these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells (8) running in the low-power mode.

Symbol	Parameter	Conditions	Speed Grade								
			-	-6		-7		-10		-15	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
fcnt	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f _{acnt}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Tables 31 and 32 show the EPM7128S AC operating conditions.

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- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade								
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		4.2		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		1.1		2.0		4.0		ns
t _{AH}	Array clock hold time		1.7		2.1		3.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF <i>(3)</i>	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.7		8.2		10.0		13.0	ns
f _{сnт}	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

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Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2)Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more (1)information on switching waveforms.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter (2)must be added to this minimum width if the clear or reset signal incorporates the t_{IAD} parameter into the signal path.

This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This (3) parameter applies for both global and array clocking.

These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB. (4)

- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use. (6)

For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, (7) these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8)The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

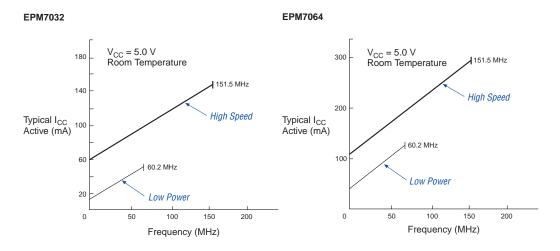
Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15		1		
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns		
t _{CH}	Global clock high time		3.0		4.0		5.0		ns		
t _{CL}	Global clock low time		3.0		4.0		5.0		ns		
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns		

Symbol	Parameter	Conditions	Speed Grade							
			-7		-10		-15		1	
			Min	Мах	Min	Max	Min	Max		
t _{AH}	Array clock hold time		1.8		3.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			8.0		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	125.0		100.0		76.9		MHz	
t _{ACNT}	Minimum array clock period			8.0		10.0		13.0	ns	
f _{acnt}	Maximum internal array clock frequency	(4)	125.0		100.0		76.9		MHz	
f _{MAX}	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz	

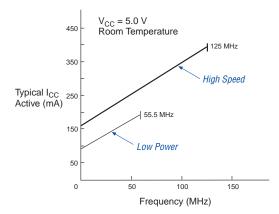
Table 36. EPM7192S Internal Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns		
t _{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns		
t _{FIN}	Fast input delay			3.2		1.0		2.0	ns		
t _{SEXP}	Shared expander delay			4.2		5.0		8.0	ns		
t _{PEXP}	Parallel expander delay			1.2		0.8		1.0	ns		
t _{LAD}	Logic array delay			3.1		5.0		6.0	ns		
t _{LAC}	Logic control array delay			3.1		5.0		6.0	ns		
t _{IOE}	Internal output enable delay			0.9		2.0		3.0	ns		
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns		
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns		
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		7.0	ns		
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns		
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns		
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns		
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns		
t _{SU}	Register setup time		1.1		2.0		4.0		ns		

Figure 14 shows typical supply current versus frequency for MAX 7000 devices.





EPM7096



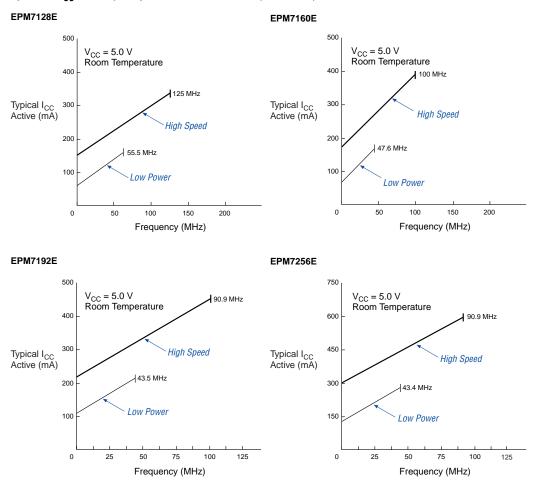


Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 2 of 2)

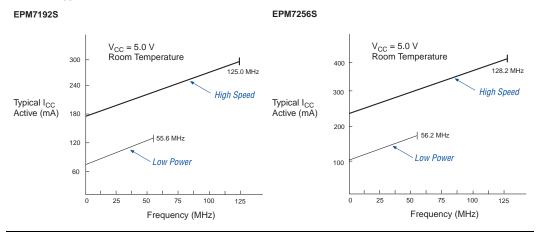


Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)

Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.